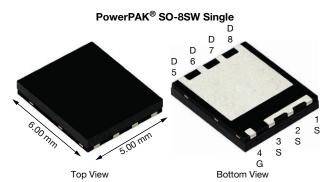
Vishay Siliconix

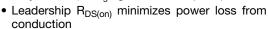
# N-Channel 60 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.00115			
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 7.5 \text{ V}$	0.0013			
Q <sub>g</sub> typ. (nC)	81			
I <sub>D</sub> (A) <sup>a</sup>	373			
Configuration	Single			

#### **FEATURES**

- TrenchFET® Gen IV power MOSFET
- Very low R<sub>DS</sub> x Q<sub>a</sub> figure-of-merit (FOM)

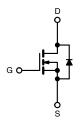




- 100 % R<sub>a</sub> and UIS tested
- Enhance power dissipation and lower RthJC
- Wettable flank to improved solderability
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- Synchronous rectification
- DC/DC converters
- OR-ing and hot swap switch
- Power supplies
- · Motor drive control
- Battery management



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK® SO-8SW
Lead (Pb)-free and halogen-free	SiRS4600EPW-T1-RE3

ABSOLUTE MAXIMUM RATING	<b>S</b> (T <sub>A</sub> = 25 °C, u	nless other	wise noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	60	V	
Gate-source voltage		$V_{GS}$	± 20	v	
Continuous drain current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 25 °C		373		
	T <sub>C</sub> = 70 °C	1	312		
	T <sub>A</sub> = 25 °C	I <sub>D</sub>	65 b, c		
	T <sub>A</sub> = 70 °C		54 <sup>b, c</sup>	^	
Pulsed drain current (V <sub>GS</sub> = 10 V, t = 100 μs)		I <sub>DM</sub>	500	A	
Continuous source-drain diode current	T <sub>C</sub> = 25 °C		303		
Continuous source-drain diode current	T <sub>A</sub> = 25 °C	l <sub>S</sub>	9.1 <sup>b, c</sup>		
Single pulse avalanche current	1 0.1 mll	I <sub>AS</sub>	68		
Single pulse avalanche energy	L = 0.1 mH	E <sub>AS</sub>	231	mJ	
	T <sub>C</sub> = 25 °C		333		
Maying up navyar discination	T <sub>C</sub> = 70 °C		233	w	
Maximum power dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	10 b, c	VV	
	T <sub>A</sub> = 70 °C		7 b, c		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	-°C	
Soldering recommendations (peak temperature) <sup>c</sup>		Ĭ	260		

THERMAL RESISTANCE RATING	S				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient b	t ≤ 10 s	$R_{thJA}$	10	15	°C/W
Maximum junction-to-case (drain)	Steady state	R <sub>thJC</sub>	0.3	0.45	C/VV

### Notes

- a.  $T_C = 25 \,^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8SW is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- f. Maximum under steady state conditions is 45 °C/W



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					•	
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 10 mA	-	31	-	
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-8.8	-	mV/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2	-	4	V
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Zana and a silvan darka a sanat		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	-	-	1	μA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	-	-	10	
		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	0.00091	0.00115	
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 7.5 \text{ V}, I_D = 20 \text{ A}$	-	0.00103	0.0013	Ω
Forward transconductance a	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 45 \text{ A}$	-	140	-	S
Dynamic <sup>b</sup>						
Input capacitance	C <sub>iss</sub>		-	7655	-	
Output capacitance	C <sub>oss</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	1775	-	pF
Reverse transfer capacitance	C <sub>rss</sub>		-	57	-	
		$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	108	162	
Total gate charge	Qg		-	81	122	
Gate-source charge	Q <sub>qs</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 20 A		33	-	nC
Gate-drain charge	Q <sub>gd</sub>		-	14	-	
Output charge	Q <sub>oss</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	-	111	-	
Gate resistance	$R_{g}$	f = 1 MHz	0.24	1.2	2.4	Ω
Turn-on delay time	t <sub>d(on)</sub>		-	21	40	
Rise time	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_L = 3 \Omega, I_D \cong 10 \text{ A},$	-	13	25	- - -
Turn-off delay time	t <sub>d(off)</sub>	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	45	90	
Fall time	t <sub>f</sub>		-	10	20	
Turn-on delay time	t <sub>d(on)</sub>		-	25	50	ns
Rise time	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_L = 3 \Omega, I_D \cong 10 \text{ A},$	-	23	50	
Turn-off delay time	t <sub>d(off)</sub>	$V_{GEN} = 7.5 \text{ V}, R_g = 1 \Omega$	-	40	80	
Fall time	t <sub>f</sub>		-	10	20	
<b>Drain-Source Body Diode Characteristic</b>	cs			•		
Continuous source-drain diode current	Is	T <sub>C</sub> = 25 °C	-	-	303	۸
Pulse diode forward current	I <sub>SM</sub>		-	-	500	Α
Body diode voltage	$V_{SD}$	$I_S = 10 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.70	1.1	V
Body diode reverse recovery time	t <sub>rr</sub>		-	70	140	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	132	260	nC
Reverse recovery fall time	t <sub>a</sub>	$T_J = 25  ^{\circ}\text{C}$	-	42	-	
Reverse recovery rise time	t <sub>b</sub>		-	28	-	ns

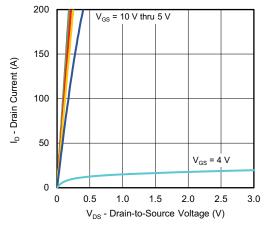
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

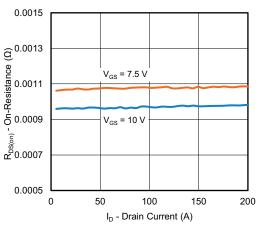
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



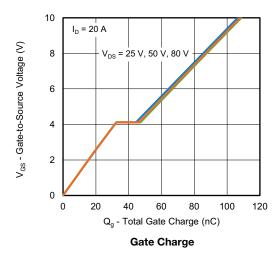
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

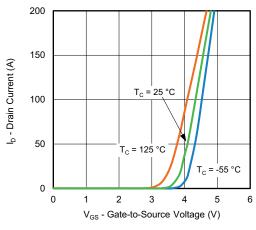


#### **Output Characteristics**

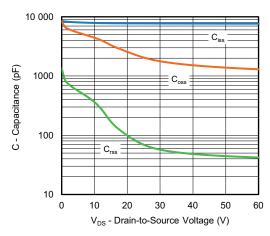


On-Resistance vs. Drain Current and Gate Voltage

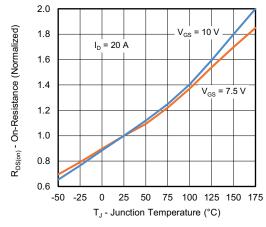




**Transfer Characteristics** 



Capacitance



On-Resistance vs. Junction Temperature



0.005

0.004

0.003

0.002

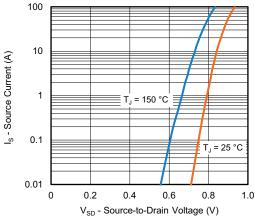
0.001

0

2

- On-Resistance (Ω)

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### Source-Drain Diode Forward Voltage



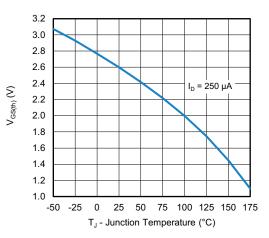
T<sub>J</sub> = 125 °C

8

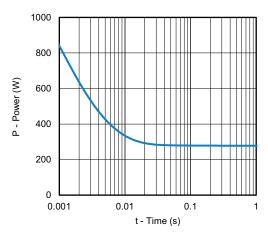
10

T<sub>J</sub> = 25 °C

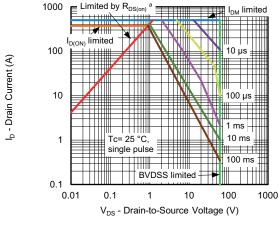
6



**Threshold Voltage** 



Single Pulse Power, Junction-to-Case



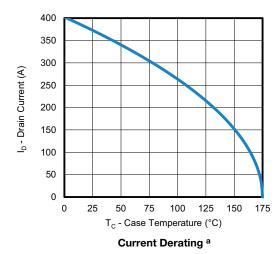
Safe Operating Area, Junction-to-Case

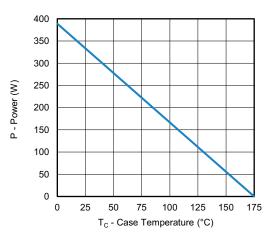
## Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

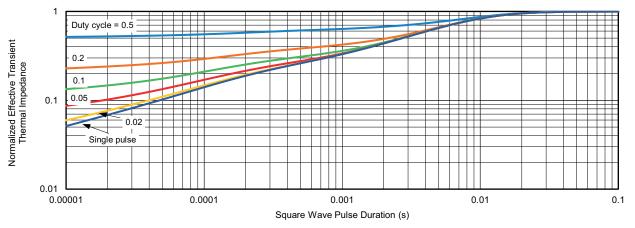




Power, Junction-to-Case

#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



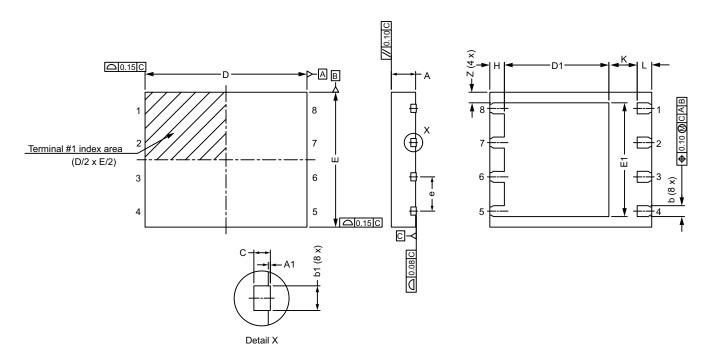
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?61680">www.vishay.com/ppg?61680</a>.



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# PowerPAK® SO-8S BWL

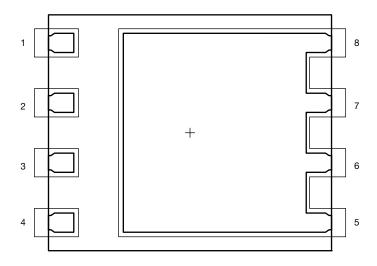


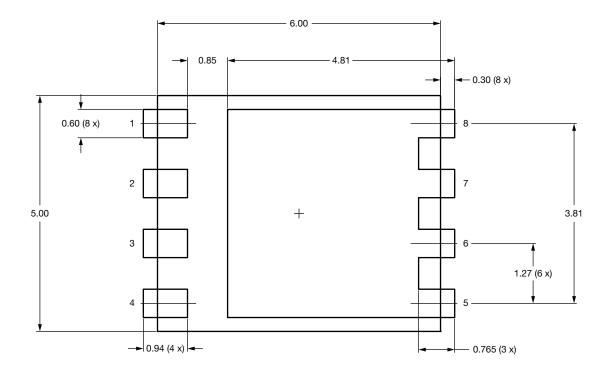
DIM.		MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	0.85	0.90	0.95	0.033	0.035	0.037		
A1	-	-	0.05	-	-	0.002		
b	0.31	0.41	0.51	0.012	0.016	0.020		
b1	0.20	0.30	0.40	0.008	0.012	0.016		
С		0.20 ref.			0.008 ref.			
D	5.90	6.00	6.10	0.232	0.236	0.240		
D1	3.78	3.88	3.98	0.149	0.153	0.157		
E	4.90	5.00	5.10	0.193	0.197	0.201		
E1	4.12	4.22	4.32	0.162	0.166	0.170		
е		1.27 BSC			0.050 BSC			
Н	0.44	0.54	0.64	0.017	0.021	0.025		
K		1.05 ref.			0.041 ref.			
L	0.44	0.54	0.64	0.017	0.021	0.025		
Z		0.39 ref.			0.015 ref.			

DWG: 6082



# Recommended Land Pattern PowerPAK® SO-8S BWL







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